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Amendment to the Claims

1-7. (Cancelled)

8. (Currently Amended) A method of processing a substrate, comprising:

processing a substrate with a substrate processing liquid and then cleaning a reverse side surface of the substrate with a cleaning liquid supplied from a first reverse side nozzle connected to a first cleaning liquid supply line while circumferentially surrounding the substrate, held by a substrate holder, with a tapered portion of a scattering prevention cup, wherein the diameter of the tapered portion is progressively larger in a downward direction of the scattering prevention cup so as to prevent a substrate the substrate processing liquid and the cleaning liquid supplied to the substrate from being scattered around;

lowering the scattering prevention cup until an upper surface of the scattering prevention cup lies substantially on the same place same plane as an upper surface of the substrate held by the substrate holder so as to circumferentially surround the substrate held by the substrate holder with a smaller-diameter portion that is connected to an upper end of the tapered portion of the scattering prevention cup;

cleaning the substrate which has been processed by the processing liquid; and horizontally supplying a cleaning liquid from a second reverse side nozzle connected to a second cleaning liquid supply line to the substrate holder in a direction toward the scattering prevention cup while rotating the substrate holder, so that the cleaning liquid from the reverse side nozzle cleans a substantially entire inner wall surface of the scattering prevention cup and an upper

surface of the substrate holder.

9-12. (Cancelled)